

BEST AVAILABLE COPY

PTO/SB/08A (10-01)

Approved for use through 10/31/2002. OMB 0851-0031
U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	10/626718
				Filing Date	July 25, 2003
				First Named Inventor	MIURA et al.
				Art Unit	Unassigned 2818
				Examiner Name	Unassigned LONG TRAN
Sheet	1	of	1	Attorney Docket Number	500.33045CC3

U.S. PATENT DOCUMENTS					
Examiner Initials ¹	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
LKT		US-4,839,306	06/1989	Wakamatsu	
LKT		US-4,842,675	06/1989	Chapman et al.	
LKT		US-4,860,070	08/1989	Arimoto et al.	
LKT		US-4,890,147	12/1989	Teng et al.	
LKT		US-5,079,181	01/1992	Shimizu et al.	
LKT		US-5,258,332	11/1993	Horioka et al.	
LKT		US-5,293,512	03/1994	Nishigoori et al.	
LKT		US-5,298,782	05/1994	Sundaresan	
LKT		US-5,329,138	07/1994	Mitani et al.	
LKT		US-5,332,683	07/1994	Miyashita et al.	
LKT		US-5,386,131	01/1995	Sato	
LKT		US-5,428,239	06/1995	Okumura et al.	
LKT		US-5,461,248	10/1995	Jun	

FOREIGN PATENT DOCUMENTS					
Examiner Initials ¹	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Country	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)			
LKT		JP 3-96249	04/1991	Japan (Abstract only)	
LKT		JP 3-236283	10/1991	Japan	
LKT		JP 4-127433	04/1992	Japan (Abstract only)	

OTHER DOCUMENTS

Miura et al., "Residual Stress Measurement in Silicon Substrates after Thermal Oxidation", JSME Int'l Journal, Series A, Vol. 36, No. 3, 1993, pages 302-308
Wolf, "Fully Recessed Oxide Locos Processes", Silicon Processing for the VLSI Era, Vol. II, page 28, 2.3
Saito et al., "Development of a Stress Simulation Program For Semiconductor Devices Considering Their Fabricating Process", Computational Mechanics '91 Proc. of Int. Conf. on Comp. Eng. Sci. 1991, pages 880-883
Saito et al., "A Two-Dimensional Thermal Oxidation Simulator Using Visco-Elastic Stress Analysis", IEDM, 1989, pages 695-698
Magdo et al., "Framed Recess Oxide Scheme For Dislocation-Free Planar Si Structures", SOLID-STATE SCIENCE AND TECHNOLOGY, Vol. 125, No. 6, 1978, pages 932-936
Chiu et al., "A Bird's Beak Free Local Oxidation Technology Feasible for VLSI Circuits Fabrication", IEEE TRANSACTIONS ON ELECTRON DEVICES, Vo. ED-29, No. 4, 1983, pages 536-540

Examiner Signature	LONG TRAN	Date Considered	11/01/04
--------------------	-----------	-----------------	----------

¹EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

²Applicant's unique citation designation number (optional). ³See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ⁴Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁵For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁶Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁷Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.